

9. (New) A semiconductor dynamic sensor, comprising:

a substrate;

a sensor chip, including a movable member for sensing a dynamic force applied thereto, for generating sensor signals proportional to an amount of movement of the movable member; and

a film located between the substrate and the sensor chip for bonding a surface of the sensor chip with a surface of the substrate.

10. (New) The semiconductor dynamic sensor of claim 9, wherein the substrate

comprises a circuit chip electrically connected to the sensor chip for processing the sensor signals generated by the sensor chip.

11. (New) The semiconductor dynamic sensor of claim 9, wherein the film comprises one of a thermosetting and a thermoplastic resin film.

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